


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/17/10000	
<b>1.3 Title of PCN</b>	Flip-chip BGA package assembly transfer from SCC to JSCC for STIH310 products.	
<b>1.4 Product Category</b>	STIH310 flipchips family.	
<b>1.5 Issue date</b>	2017-01-06	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	FRANK WOLINSKI
<b>2.1.2 Phone</b>	+49 89460062287
<b>2.1.3 Email</b>	frank.wolinski@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Stephane MOUGIN
<b>2.1.2 Marketing Manager</b>	Pascal AUDIFFREN
<b>2.1.3 Quality Manager</b>	Pascal SCAFIDI

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site	Assembly site	JSCC Shanghai

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Production at StatsChippacChina.	New Production at JSCC Shanghai.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	NO	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	New source due to factory demolition.
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	New Finished goods code creation.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2016-11-18
<b>7.2 Intended start of delivery</b>	2016-12-18
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	Qual plan FCBGA copper pillar for xfer SCC to JSCC - DPG0116-QP-3 1.docx		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2017-01-06

**9. Attachments (additional documentations)**

10000 Public product.pdf  
Qual plan FCBGA copper pillar for xfer SCC to JSCC - DPG0116-QP-3 1.docx

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STIH412-BJB	
	STIH412-EJB	

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